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# 激光和 TIG 堆焊钴基合金的性能

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摘 要: 为了提高马氏体不锈钢蒸汽涡轮叶片的性能 采用 Nd: YAG 激光、 $CO_2$  激光、半导体激光和 TIG 堆焊方法 在 12% Cr 马氏体不锈钢表面堆焊了钴基合金粉末( Stellite-6) . 通过 X 射线衍射分析、电子探针分析、能谱分析和耐磨试验 研究了堆焊层的形状、稀释率、维氏硬度、DAS( 枝晶间距) 值、显微组织和耐磨性能 ,并比较了不同堆焊方法的特点 . 与 TIG 堆焊相比 激光堆焊方法的堆焊层具有更小的稀释率、细小的显微组织、狭窄的热影响区、高的维氏硬度、优良的耐磨性、高的钴含量和低的铁含量的特点.

关键词: 激光堆焊; 显微组织; 维氏硬度; 耐磨性; 稀释率

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# 0 序 言

由于激光堆焊对混合型合金粉末的适应能力强、堆焊层稀释率低、热输入小,并且可以通过对离焦量、堆焊速度和送粉量等的控制获得低稀释率的堆焊层. 所以,用激光堆焊可将合金粉末堆焊于廉价的基体材料表面上,从而制造出具有更高性能的堆焊层,以提高零部件的使用性能和使用寿命. 马氏体不锈钢(SUS403)因具有较高的耐热性,经常用于刀具、蒸汽涡轮叶片、轴承等制造. 钴基合金(Stellite-6)具有很高的耐腐蚀性、耐气蚀性、耐磨性及耐高温性等,因此通常将其堆焊层应用于极其苛刻的工况环境中[1-4].

传统的强化和修复方法是用银钎焊或 TIG 焊将 Stellite-6 板条焊到不锈钢涡轮叶片上. 但由于钎焊接合强度低及 TIG 焊变形大等问题 ,所以远远满足不了使用性能上的要求. 为了进一步提高马氏体不锈钢涡轮叶片的耐腐蚀性能、耐热性能和耐气蚀性能及减少焊接变形 ,作者采用了脉冲 Nd: YAG 激光 ,CO<sub>2</sub> 激光 ,半导体激光和 TIG 等不同的热源将 Stellite-6 合金粉末堆焊于马氏体不锈钢表面 ,并用比较的方法分析了各种堆焊方法的特性.

# 1 试验方法

## 1.1 试验设备及材料

TIG 堆焊设备型号为 DIHENINVERTER ARGO

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300P DC-EX. TIG 堆焊和激光堆焊的条件分别如表 1和表 2 所示. 基体材料(调质处理的 SUS403)和堆焊材料(Stellite-6)的化学成分如表 3 所示.

## 1.2 堆焊层性能分析方法

用线切割截取堆焊层的横断面 研磨和抛光后,用王水腐蚀1~5 min;测量了堆焊层的宽度、高度和熔深;对堆焊层的显微组织进行了观察;对堆焊层的相结构、微区化学成分,耐磨性能、维氏硬度进行了测定及分析.

# 2 试验结果与讨论

# 2.1 堆焊层形状

用 TIG 堆焊和三种激光堆焊所获得的堆焊层的横断面及外形如图 1 所示. 测量和计算获得的堆焊层尺寸和稀释率如表 4 所示. TIG 堆焊时 ,其堆焊层横断面及焊缝外形如图 1a 所示. 当电流增大时 ,堆焊层的高度减小 ,宽度、熔深和稀释率增大 ,由表 4 可知 ,TIG 堆焊所获得的堆焊层稀释率远高于其它三种方法. 这是由于 TIG 堆焊时热输入量较大 ,而激光堆焊时热输入量较小的缘故.

脉冲 Nd: YAG 激光堆焊和连续波 CO<sub>2</sub>激光堆焊时 其横断面及焊缝外形分别如图 1b & 所示. 随着堆焊速度的增大 ,堆焊层宽度基本不变、高度减小、熔深增大. 因为堆焊层宽度主要取决于光斑直径;随着堆焊速度的增大 ,单位长度上所得到的粉末量减少 ,导致堆焊层的高度减小;同时过多的能量用来加热母材 ,因此熔深和稀释率增大.

#### 表 1 TIG 堆焊工艺条件

Table 1 Condition of TIG cladding

 试样 编号	焊接电流 (连续) //A	电弧电压 <i>U/</i> V	堆焊速度 v/( m•min <sup>-1</sup> )	热输入 E/( kJ•cm <sup>-1</sup> )	电极直径 D/mm	焊枪倾斜角度 α/(°)	焊丝直径 r/mm	焊丝倾角 β/(°)
T100	100	10 ~ 12	0.048 ~ 0.072	12	2.4	70 ~ 80	2.0	35
T120	120	10 ~ 12	$0.048 \sim 0.072$	15	2.4	70 ~ 80	2.0	35

#### 表 2 激光堆焊工艺条件

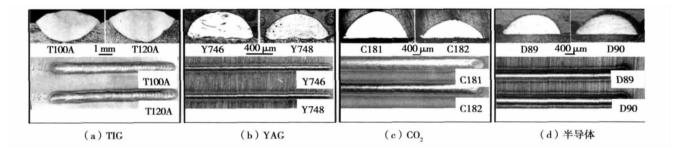
Table 2 Condition of laser cladding

试样	激光	输出	额定功率	激光功率	焦点尺寸	离焦量	堆焊速度	热输入	功率密度	送粉量
编号	类型	形式	$P_{{f ar a}ar {ar V}}$	$P/\mathbb{W}$	$d/\mathrm{mm}$	$Z/\mathrm{mm}$	v/( m•min -1)	$E/(kJ \cdot cm^{-1})$	$E_{\rm p}$ /( W•mm $^{-2}$ )	$M_{\rm p}$ /( g•min $^{-1}$ )
Y746	Nd: YAG	脉冲	1 800	200	1.5	3.5	0.10	1.2	113.2	8.0
Y748	Nd: YAG	脉冲	1 800	200	1.5	3.5	0.30	0.4	113.2	8.0
C181	$CO_2$	连续	4 000	3 000	5.7	25.0	0.80	3.0	117.6	29.4
C182	$CO_2$	连续	4 000	3 000	5.7	25.0	1.00	1.8	117.6	29.4
D89	半导体	连续	2 500	500	$1.0 \times 2.7$	0	0.40	0.75	185.1	11.86
D90	半导体	连续	2 500	600	$1.0 \times 2.7$	0	0.40	0.9	222.2	11.86

# 表3 基体及堆焊层材料的化学成分(质量分数 %)

Table 3 Chemical compositions of substrates and cladding material

	С	Si	Mn	S	P	Ni	Cr	Co	Fe	W	尺寸
SUS403	≤0.15	≤0.5	≤1	≤0.03	≤0.04	_	11.5 ~ 13	_	余量	_	80 mm × 30 mm × 12 mm
Stellite-6( 粉末)	1.20	1.3	0.01	_	_	1.3	28.0	余量	1.4	4.7	$-38 \sim 150~\mu m$
Stellite-6( 焊丝)	1.15	1.1	0.06	_	_	_	28.2	余量	1.3	4.0	ф2.0 mm



## 图 1 TIG 和激光堆焊层的横断面及外形

Fig. 1 Cross section morphologies of TIG and laser cladding layers

表 4 TIG 和激光堆焊层尺寸及稀释率

Table 4 Bead shapes and dilution of TIG and laser cladding

 试样编号	工艺方法	激光功率 P/W	焊接速度 $v_1$ /( m•min -1)	宽度 B/mm	高度 H/mm	深度 h/mm	稀释率 ω( %)
T100A	TIG	1 100	0.048 ~ 0.072	4.573	0.793	1.25	61.18
T120A	TIG	1 320	0.048 ~ 0.072	5.046	0.696	1.465	67.79
Y746	YAG 激光	200	0.1	1.00	0.50	0.04	6.42
Y748	YAG 激光	200	0.3	0.90	0.42	0.05	10.23
C181	CO <sub>2</sub> 激光	3 000	0.8	3.37	1.29	0.07	5.15
C182	CO <sub>2</sub> 激光	3 000	1.0	3.28	0.86	0.07	7.53
D89	半导体激光	500	0.4	2.31	0.72	0.03	4.38
D90	半导体激光	600	0.4	2.36	0.75	0.07	6.89

半导体激光堆焊时,其堆焊层的横断面及焊缝外形如图 1d 所示,D89 和 D90 的激光输出功率分别为 500 W 和 600 W. 随着激光输出功率的增大,堆焊层的宽度、高度、熔深和稀释率略有增加,但其稀释率都较小.

输出功率为 3 kW 时 , $CO_2$  激光堆焊层宽度为 3. 28 ~3. 37 mm; 输出功率为 500 ~600 W 时 ,半导体激光堆焊层宽度为 2. 31 ~2. 36 mm.  $CO_2$  激光堆焊与半导体激光堆焊相比 ,虽然激光输出功率相差

很大,但堆焊层宽度的差别却不大. 另外,半导体激光堆焊与其它激光堆焊相比,由于半导体激光在聚焦点的矩形光斑(1.0×2.7 mm)上能量密度分布较均匀,所以更易获得低稀释率和较宽的堆焊层.

# 2.2 堆焊层的显微组织

TIG 堆焊和三种激光堆焊所获得的堆焊层熔合线附近及堆焊层上部的显微组织分别如图 2、图 3 所示. 由金相照片可知 ,它们均为亚共晶组织 ,即由初晶固溶体和共晶组织构成<sup>[5]</sup>.

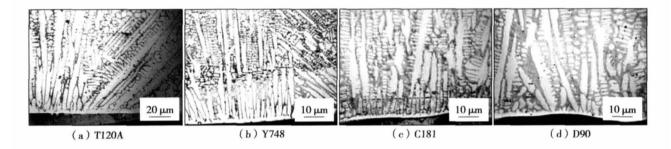


图 2 TIG 和激光堆焊层熔合线附近的显微组织

Fig. 2 Microstructure near fusion line of clad layer in TIG and laser cladding

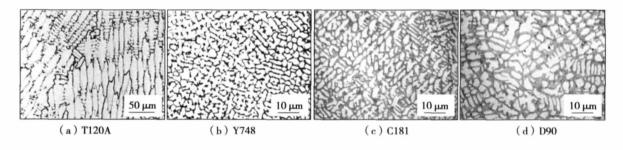


图 3 TIG 和激光堆焊层上部的显微组织

Fig. 3 Microstructure near top surface of clad layer in TIG and laser cladding

## 2.2.1 熔合线附近的显微组织

TIG 堆焊和三种激光堆焊的熔合线附近显微组织如图 2 所示. 由于从熔合线到堆焊层表面的凝固速度  $v_s$  逐渐增加 ,温度梯度 G 逐渐减小 ,所以四种堆焊方法从熔合线到堆焊层表面的组织形态依次均由平面晶生长、胞状晶生长、柱状晶生长、等轴晶生长构成. 试样 T120A ,Y748 ,C181 和 D90 的枝晶臂间距( DAS) 值分别为 22. 68 A. 82 ,10. 33 和 9. 87 mm ,DAS 值越大 ,说明初晶相尺寸越粗大. 由上述结果可知 ,与 TIG 堆焊层相比 激光堆焊层的组织细小. 这是由于 TIG 堆焊的热输入比较大 ,导致  $G/v_R$  ( G-温度梯度、 $v_R$ -晶粒生长速度) 值小 ,所以更易形成粗大组织<sup>[6]</sup>.

### 2.2.2 堆焊层上部的显微组织

TIG 堆焊和三种激光堆焊层上部的显微组织如图 3 所示. 可知, 堆焊层上部组织基本上均由等轴

晶组成. 这是由于堆焊层上部的温度梯度 G 小,而晶粒凝固速率 R 快的缘故,导致过冷度较大 $^{[7\ 8]}$ ,所以容易形成等轴晶.

试样 T120A ,Y748 ,C181 和 D90 的等轴晶 DAS 值分别为 20.33  $\rlap{4}$ .01  $\rlap{3}$ .61 和 7.78 mm. 由上述结果可知 ,与 TIG 堆焊相比 激光堆焊能够获得更加细小的晶粒. 试样 D90 的 X 射线衍射分析结果如图 4 所示. 由试验结果可知 ,堆焊层由富钴固溶体  $Cr_{23}$   $C_6$  , $Co_3$   $W_3$  C 和 WC 相组成.

电子探针成分分析结果如图 5 所示. 与共晶组织相比. 初晶固溶体相含有较多的钴、铁和较少的碳、铬、钨. 由上述分析可知,亚共晶组织的初晶相是由富钴固溶体组成,共晶组织由富钴固溶体、 $Cr_{23}C_6$ ,  $Co_3W_3C$  和 WC 相组成. 堆焊层的扫描电镜形貌如图 6 所示,由微区成分分析结果可知,TIG 和激光堆焊层的共晶组织中均存在  $Cr_{23}C_6$ 相等.

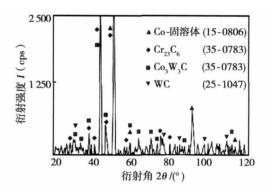


图 4 激光堆焊层的 X 射线衍射分析结果 Fig. 4 Results of X-ray diffraction analysis of laser cladding layer

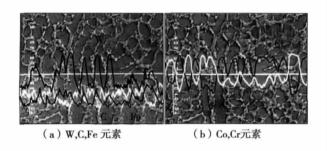
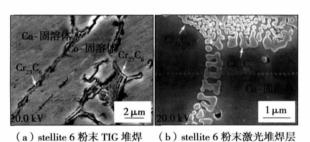


图 5 堆焊层中 Co, W, Cr, C, Fe 元素的电子探针成分分析

Fig. 5 Results of EPMA line analysis of Co, W, Cr, C, and Fe in clad layer



(a) stellite 6 粉末 TIG 堆焊

图 6 共晶组织中 Cr23 C6相的扫描电镜图像 Fig. 6 SEM of Cr<sub>23</sub>C<sub>6</sub>phase in eutectic structure

由以上分析可知,四种堆焊方法所获得的显微 组织均为亚共晶组织. 由于 TIG 堆焊时热输入大, 与激光堆焊相比 更容易形成粗大的组织; 堆焊层上 部显微组织 由于其过冷度较大 因此比同种方法所 获得的堆焊层中晶粒细小 易形成等轴晶组织.

### 2.3 堆焊层内合金元素的分布

对四种堆焊方法所获得的堆焊层进行了电子探 针成分分析 其结果如图 7 所示. 由图 7 可知 Co 和 Fe 元素的含量从熔合线到基体材料方向几乎没有 变化. 从熔合线到堆焊层方向 ,Co 和 Fe 元素在熔 合线附近的分布变化则非常显著,但是经过熔合区

后,试样 T120A 堆焊层的铁含量远远高干试样 Y748 C181 和 D90; 试样 D90、C181 和 Y748 堆焊层 的钴含量较接近 "几乎是试样 T120A 的 1.7 倍.

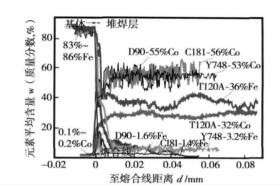


图 7 TIG 和激光堆焊层的电子探针分析结果 Fig. 7 Results of EPMA analysis of clad layer in TIG and laser cladding

由以上分析可知,由于基体对堆焊层有稀释作 用 导致 Co 和 Fe 元素沿熔合线到堆焊层方向分布 变化非常显著 但由于基体热影响区几乎不受稀释 作用的影响 因此 Co 和 Fe 元素的含量从熔合线到 基体材料方向几乎没有变化. 且由于 TIG 堆焊的热 输入量比较大 基体材料熔化量较大 因此其堆焊层 中 Fe 元素含量较高 而 Co 元素的含量较低.

#### 2.4 堆焊层的硬度

四种堆焊方法所获得的堆焊层硬度分布如图 8 所示. 由试验结果可知,试样 T120A,Y748,C181, D90 的热影响区宽度分别为 2.5 0.38 0.35 和 0.59 mm. 激光堆焊热输入量小,其功率密度通常比 TIG 焊高一个数量级以上 导致其聚焦成很小的束斑 因 此热影响区狭窄. 另外,由试验结果可知,TIG 堆焊 层与其热影响区硬度几乎相同,约为4.0~4.5 GPa; 脉冲 Nd: YAG 激光、CO。激光和半导体激光堆 焊层的硬度分别为 6.4 6.5 和 6.7 GPa. 与 TIG 堆 焊层相比 激光堆焊层具有更高的硬度.

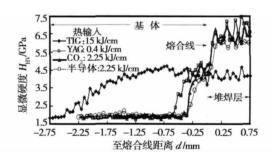


图 8 TIG 和激光堆焊层的硬度分布 Fig. 8 Hardness distribution of clad layer in TIG and laser cladding

由以上分析可知,激光堆焊由于其光斑直径小 且热输入小,导致其热影响区远小于 TIG 堆焊. 另外,由于激光堆焊所获得的堆焊层组织细小,且稀释 率低,因此激光堆焊层的硬度高于 TIG 堆焊层.

### 2.5 堆焊层的耐磨性

四种堆焊方法多道堆焊层的外观和横断面如图 9 所示. 通过对四种堆焊方法获得的多道堆焊层

的外观和横断面的检测,结果均获得了无缺陷和美观的外形. 用大越式磨损试验机对堆焊试样进行磨损试验. T120A,Y748,C181 和 D90 的磨损率分别为1.9,1.42,1.12 和0.8(10<sup>-8</sup> mm²/kg). 与 TIG 堆焊相比 激光堆焊层的磨损率较低,耐磨性较好,这也是由于激光堆焊热输入小,导致组织细化且稀释率低的缘故.

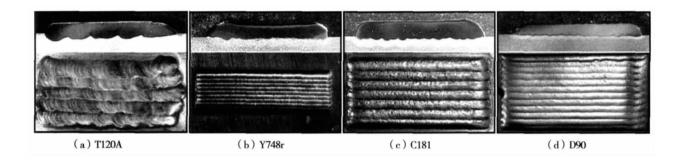


图 9 TIG 和激光多道堆焊层 Fig. 9 Multi-pass clad layer of TIG and laser cladding

# 3 结 论

- (1) TIG 堆焊层的稀释率为 61.2% ~ 67.8%, 激光堆焊层的稀释率为 4.4% ~ 10.2%. 因半导体激光聚焦点的矩形光斑上能量密度分布较均匀,所以更易获得低稀释率和较宽的堆焊层.
- (2) TIG 堆焊和三种激光堆焊所获得的堆焊层组织均为亚共晶组织; 初晶相由富钴固溶体组成 ,共晶组织由富钴固溶体、 $Cr_{23}C_6$ 、 $Co_3W_3C$  及 WC 相组成. TIG 堆焊初晶相 DAS 值为 20.3 ~ 22.7 mm; 激光堆焊初晶相 DAS 值为 3.6 ~ 10.3 mm.
- (3) 激光堆焊层的硬度是 TIG 堆焊层的 1.5 倍左右; 激光堆焊层的耐磨性能是 TIG 堆焊层的1.3 ~ 2.4 倍.

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**Key words**: nanobainite steel; microstructure; brittle intercrystalline fracture; microhardness; weld segregation

Low temperature sintering-bonding using mixed Cu + Ag nanoparticle paste for packaging application ZHANG Yingchuan<sup>1</sup>, YAN Jianfeng<sup>1</sup>, ZOU Guisheng<sup>1</sup>, BAI Hailin<sup>1</sup>, LIU Lei<sup>1</sup>, WU Aiping<sup>1</sup>, YAN Jiuchun<sup>2</sup>, ZHOU Yunhong<sup>1,3</sup> (1. Department of Mechanical Engineering, Tsinghua University, Beijing 100084, China; 2. State Key Laboratory of Advanced Welding and Joining, Harbin Institute of Technology, Harbin 150001, China; 3. Department of Mechanical and Mechatronics Engineering, University of Waterloo, Bom in ANN, N2L 3G1, Canada). pp 17 – 21

Abstract: In this study , the two kinds of nanoparticle pastes were prepared by using the modified polyol chemical reduction process , respectively , and the mixed nanoparticle paste was prepared by mechanically mixing of the two pastes. The sintering characteristics of the mixed paste were investigated , and the results show that the mixed paste had good oxidation resistance. Ag-coated copper bulks were bonded through the sintering of mixed paste. The results indicate that the increasing of Ag content in the paste was beneficial to high quality of joints , and with the bonding conditions of sintering at 250 °C for 5 min under 5 MPa pressure , the average shear strengths of joints using nano–Cu paste , mixed paste consisting of 50% mole Ag and 50% mole Cu , and nano–Ag paste , were 15 MPa , 22 MPa and 56 MPa , respectively.

**Key words**: mixed nanoparticle paste; shearing strength; sintering temprature; mole ratio

Characteristics of Co-based clad layer formed by laser and TIG cladding XU Guojian<sup>1</sup>, HUANG Xue<sup>1</sup>, HANG Zhengxiang<sup>1</sup>, FU Xinhao<sup>1</sup>, YU Enhong<sup>2</sup> (1. School of Materials Science and Engineering, Shenyang University of Technology, Shenyang 110870, China; 2. Shenyang Siasun Robot & Automation Co., Ltd., Shenyang 110168, China). pp 22 – 26

Abstract: In order to improve the performance of martensitic stainless steel steam turbine blade , pulsed Nd: YAG laser , CO<sub>2</sub> laser , diode laser , and TIG cladding were carried out to deposite Stellite-6 powder on the surface of 12% Cr martensitic stainless steel plate. The shape of cladding layer , dilution , Vickers hardness , dendrite arm spacing (DAS) value , microstructure and wear resistance were investigated with X-ray diffraction , EPMA , EDS and wear test. And the characteristics of different cladding processes were compared. It was found that laser cladding processes , comparing with TIG cladding , have smaller dilution rate , finer microstructure , narrower heat-affected zone , higher Vickers hardness , better wear resistance , higher Co content , and lower Fe content in the resultant cladding layer.

**Key words**: laser cladding; microstructure; Vickers hardness; wear resistance; dilution

Effect of joint height on the mechanical behaviors of microscale solder joints

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gy and Materials Engineering , Chongqing University of Science and Technology , Chongqing 401331 , China; 2. Center for Advanced Life Cycle Engineering , University of Maryland , College Park 20472 , USA) . pp 27-30 , 34

Abstract: The mechanical behaviors and failure mechanism of lead-free Sn-3.0Ag-0.5Cu micro-scale solder joints with a constant diameter of 400  $\mu m$  and a height range of 125 ~ 325 µm during quasi-static tensile and shear state were investigated at 100 °C and 25 °C with accurate dynamic mechanical analyzer DMA Q800. The experimental results show that the tensile and shear strength of all micro-scale solder joints decreased with the increasing of the joint height. However, under the same loading rate of 1N/min at 100 °C , the shear strength of solder joints was lower than the tensile strength, and the shear fracture strain was also lower than the tensile one, revealing that the shear loading was severer for micro-interconnection solder joints in electronic packaging. Nevertheless, under the same loading rate, the tensile strength and strain of micro-scale solder joints with the same size decreased with the increasing of service temperature.

**Key words**: micro-scale solder joint; Sn-3. 0Ag-0. 5Cu; joint height; mechanical behavior

Effect of temperature and coatings on the wettability of Sn–Zn-Ga-Nd lead-free solder XUE Peng¹, XUE Songbai¹, SHEN Yifu¹, LONG Weimin², ZHANG Qingke², MA Jia²(1. College of Materials Science and Technology, Nanjing University of Aeronautics and Astronautics, Nanjing 210016, China; 2. State Key Laboratory of Advanced Brazing Filler Metals & Technology, Zhengzhou Research Institute of Mechanical Engineering, Zhengzhou 450001, China). pp 31 – 34

**Abstract**: The wetting time and wetting force of Sn-Zn-Ga-Nd lead-free solder on Sn , SnBi , Au/Ni coatings under different temperatures were measured , and the effect of soldering temperature on the wettability of solders on different coatings was investigated. The results indicate that with the increase of temperature , the wetting time reduced and the wetting force increased evidently. At 240 °C , the wetting time for three coatings all met the needs of IPC standard in which the wetting time  $t_0 \leq 1$  s at wave soldering. On the other hand , the wettability of the solder was better on Sn/Cu and SnBi/Cu substrates than on Au/Ni/Cu substrate.

Key words: temperature; coating; Nd; wettability

Influence of molten pool size on burn-through during inservice welding JIA Pengyu, HAN Tao, WANG Yong (College of Mechanical and Electrical Engineering, China University of Petroleum, Qingdao 266580, China). pp 35 – 37

Abstract: In order to study the influence of the molten pool size on the burn-through during in-service welding , this paper investigated the radial deformation variation law with the change of internal pressure for different molten pools under specific temperature field with commercial software code ANSYS. The results show that when the temperature field remained constant and the internal pressure in the pipe was low , the value of radial deformation of the node , which had the highest tempera-